MMSZ5240BT1G
Plastic-Encapsulate Zener Diodes

Features

- Planar Die Construction
- 500mW Power Dissipation on Ceramic PCB
- General Purpose, Medium Current
- Ideally Suited for Automated Assembly Processes
- Available in Lead Free Version

SOD-123

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
MMSZ5240BT1G	SOD-123	HXY MOSFET	3000

Absolute Maximum Ratings(Ta=25°C)

Characteristic	Symbol	Value	Unit
Forward voltage @I_F =10mA	V_F	0.85	V
Power Dissipation	P_D	500	mW
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	556	°C/W
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55 ~ +150	°C

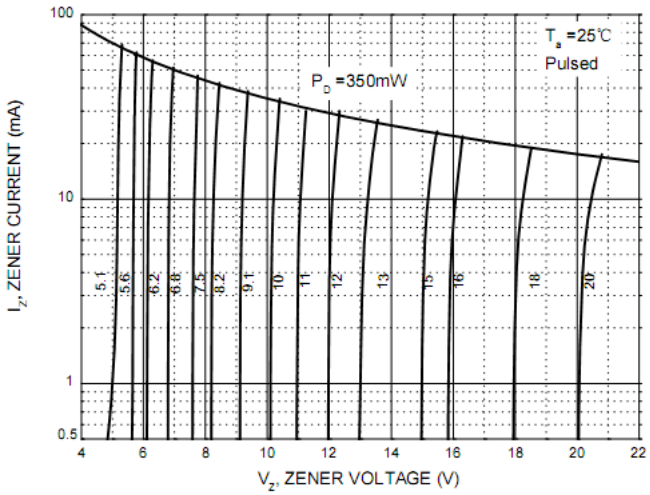
Notes: Device mounted on ceramic PCB;5.0mm×7.0mm with pad areas 35 mm²

Electrical Characteristics (Ta=25°C unless otherwise specified)

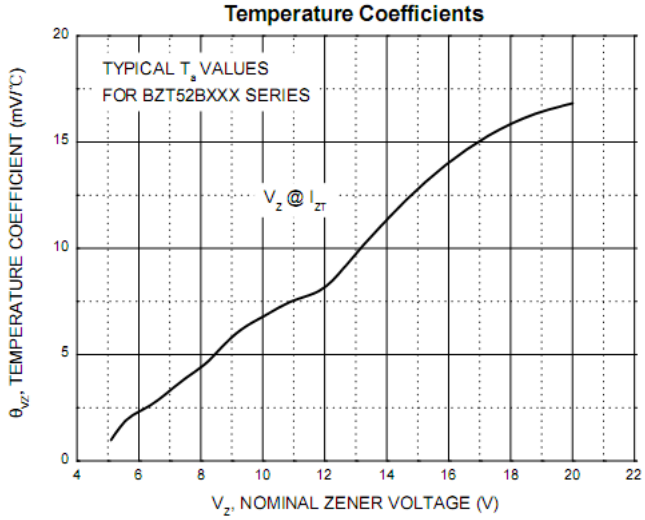
Type Number	Type Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current		Typical Temperature Coefficent @I_{ZTC}		Test Current I_{ZTC}
		V_Z@I_{ZT}			I_{ZT}	Z_{ZT}@I_{ZT}	Z_{ZK}@I_{ZK}	I_{ZK}	I_R	V_R	mV/°C		
		Nom(V)	Min(V)	Max(V)	mA	Ω		mA	μA	V	Min	Max	mA
MMSZ5240BT1G	F5	10	9.80	10.20	5	19	142.5	1.0	0.2	8.0	4.5	8.0	5

Typical Characteristics

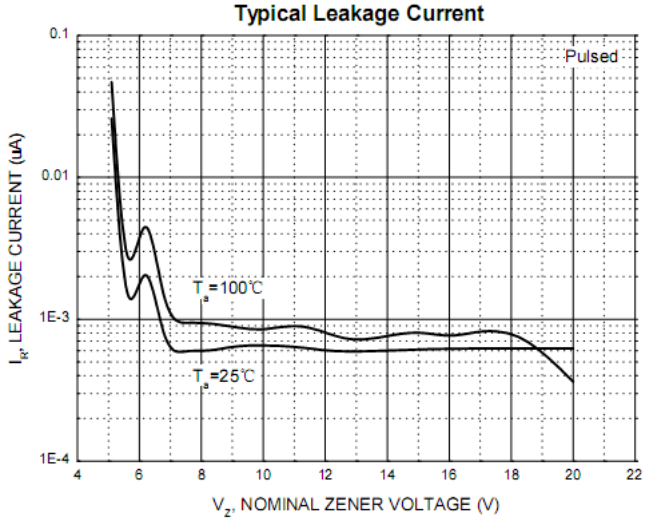
Zener Characteristics (V_Z 5.1V to 20 V)



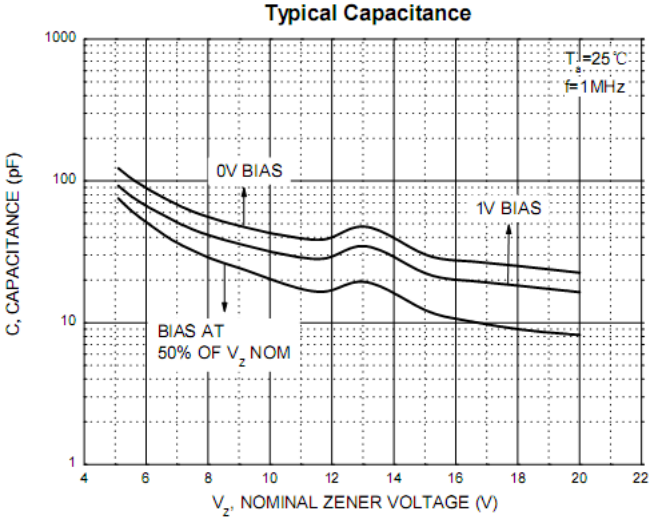
Temperature Coefficients



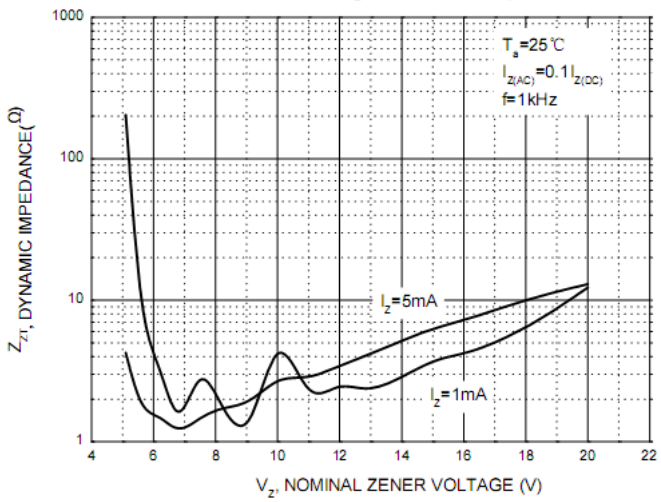
Typical Leakage Current



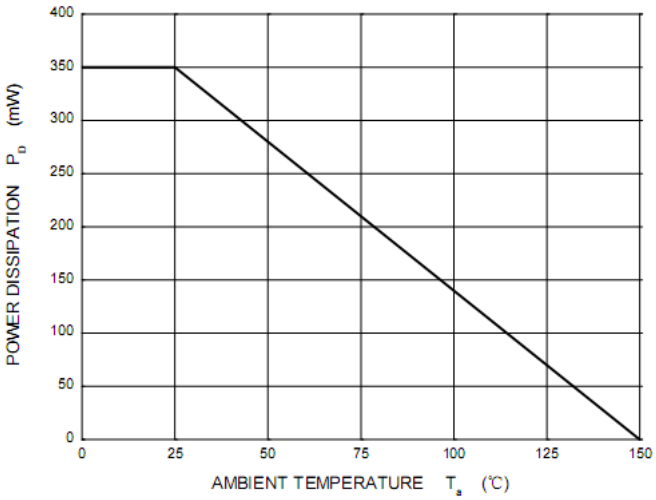
Typical Capacitance



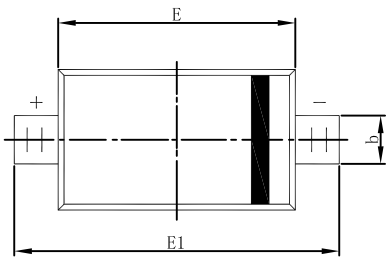
Effect of Zener Voltage on Zener Impedance

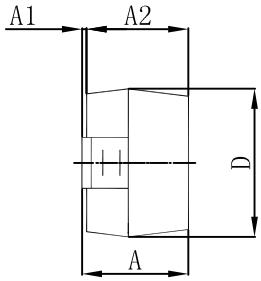


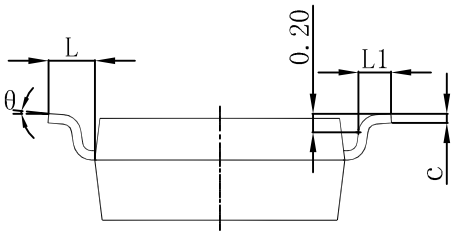
Power Derating Curve



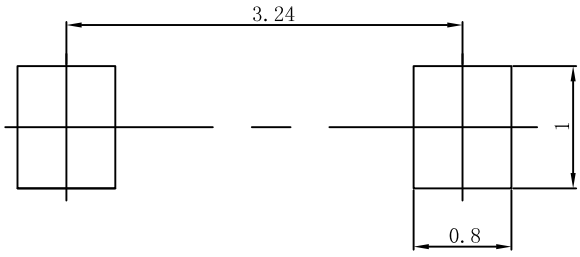
SOD-123 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.450	0.650	0.018	0.026
c	0.080	0.150	0.003	0.006
D	1.500	1.700	0.059	0.067
E	2.600	2.800	0.102	0.110
E1	3.550	3.850	0.140	0.152
L	0.500 REF		0.020 REF	
L1	0.250	0.450	0.010	0.018
θ	0°	8°	0°	8°



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

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